

L Number	Hits	Search Text	DB	Time stamp
1	1	("5614311").PN.	USPAT	2002/03/25 14:02
2	154	(chip with tape) and permeability	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:05
3	6	(chip with tape) and (water adj permeability)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:50
4	1	chip and (tape with g/m)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:11
5	15	chip and (g near m near h)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:48
6	218	(tape or substrate) with (water adj permeability)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:58
7	5	((tape or substrate) with (water adj permeability)) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:53
8	18	((tape or substrate) with (water adj permeability)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:55
9	1	((tape or substrate) with (water adj permeability)) and (chip or die)) and (g near m)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 14:56
10	9	((g/m) or (g near m)) same (water adj permeability)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:01
11	367	((g/m) or (g near m)) same permeab\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:16
12	8	((g/m) or (g near m)) same permeab\$) and (chip or die) and (tape or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:14
13	16	4971196.URPN.	USPAT	2002/03/25 15:12
14	0	20010028101.URPN.	USPAT	2002/03/25 15:14
15	2	"2001189400"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:15
16	0	2001189400.URPN.	USPAT	2002/03/25 15:15
17	0	2001189400.URPN.	USPAT	2002/03/25 15:15
18	0	2001189400.URPN.	USPAT	2002/03/25 15:15

19	3	((g/m) or (g near m)) near permeab\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:28
20	0	11080389.URPN.	USPAT	2002/03/25 15:18
21	41	(chip or die or device or semiconductor) and (board or substrate) and (polyethylene adj napthalate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:46
22	0	6197145.URPN.	USPAT	2002/03/25 15:36
23	0	6197145.URPN.	USPAT	2002/03/25 15:36
24	2	"11233567"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:42
25	0	11233567.URPN.	USPAT	2002/03/25 15:40
26	0	11233567.URPN.	USPAT	2002/03/25 15:40
27	0	11233567.URPN.	USPAT	2002/03/25 15:41
28	0	11233567.URPN.	USPAT	2002/03/25 15:41
29	0	11233567.URPN.	USPAT	2002/03/25 15:41
30	11	"612594"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:43
31	2	"6012594"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:43
32	2	"06012594"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:44
33	3	"06021594"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:44
34	10	(chip or die or (device near semiconductor)) and (board or substrate) and (polyethylene adj napthalate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:53
35	2	"11035715"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:55
36	9543	"19920911"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:56
37	3	"04257555"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 15:57
38	3	"04257444"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:07
39	15	4257444.URPN.	USPAT	2002/03/25 16:02
40	15	4257444.URPN.	USPAT	2002/03/25 16:03

41	0	"199118842"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:04
42	3	"03148472"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:12
43	24	3148472.URPN.	USPAT	2002/03/25 16:08
44	0	"20000383499"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:14
45	8	"0383499"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:13
46	0	"40383499"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:14
47	1	"04383499"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:14
48	0	"2000383499"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:17
49	3	"04257444"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:20
50	2	"9952334"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:22
51	0	"1009200"	EPO	2002/03/25 16:21
52	10	"1009200"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:21
53	10	"1009200"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:31
54	0	"EP1009200"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:32
55	12107	"19980402"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:32

56	0	"1998JP1532"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:44
57	1	("5953592").PN.	USPAT	2002/03/25 16:47
58	12	espanex	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/25 16:48
59	0	6291895.URPN.	USPAT	2002/03/25 16:48
60	0	6291895.URPN.	USPAT	2002/03/25 16:49
61	18	("4483067" "5063177" "5490324" "5602059" "5612576" "5683942" "5731231" "5737191" "5746390" "5753535" "5756379" "5834336" "5835355" "5874784" "5897337" "5950908" "5973404" "5976912").PN.	USPAT USPAT USPAT	2002/03/25 16:50